¢  $\Diamond$ 0 0 0 0  $\Diamond$  $\Diamond$  $\mathbb{R} \mathbb{R} \mathbb{R} \mathbb{R} \mathbb{R}$ 109.9 mm

User.1

```
Impedance Controlled Stackup
Differential Non-coplaner Waveguide with Ground Plane
Param | Size
 Z | 100 ohm
     | 10 mil
      | 10.22 mil
       | 1.38 mil
 H | 8.12 mil (2x3313 57% 4.2 mil)
JLCPCB: JLC04161H-3313A
```

```
Drill Map:
          0.305mm /
                                                                                          (7 holes)
- 0.305mm / 0.0120"
- 0.406mm / 0.0160"
- 0.600mm / 0.0315"
- 0.9950mm / 0.0374"
- 0.991mm / 0.0394"
- 1.000mm / 0.0430"
- 1.000mm / 0.0430"
- 1.100mm / 0.0433"
- 1.194mm / 0.0470"
- 1.295mm / 0.0689"
- 1.750mm / 0.0689"
                                                                                         (/ holes)
(68 holes)
(38 holes)
(4 holes)
(0 holes + 8 slots)
(4 holes)
(2 holes)
(7 holes)
                                                                                          (10 holes)
(4 holes)
(4 holes)
                                                                                                    holes
• 1.295mm / 0.0510 (4 notes)

• 1.750mm / 0.0689" (2 hotes)

• 1.750mm / 0.0689" (4 hotes) (not plated)

• 2.700mm / 0.1063" (4 hotes) (not plated)

• 3.400mm / 0.1339" (6 hotes) (not plated)
◆ 1.750mm / 0.0689"

◆ 2.700mm / 0.1063"
```

## NOTES:

1. Layers: 4

2. PĆB Thickness: 1.6 mm

3. PCB Color: GREEN

4. Material Type: FR-4 TG155 5. Surface Finish: ENIG 1 um

6. Outer Copper Weight: 1 oz

7. Inner Copper Weight: 0.5 oz

8. Impedance Control: YES

9. Layer Stackup: JLC04161H-3313A

10. Via Covering: Plugged11. Min Via Hole Size / Diameter:

0.406 mm / 0.81 mm

12. Board Outline Tolerance: +/- 0.2 mm 13. Silk Screen: INK-JET/SCREEN PRINTING

14. Stencil Framwork: YES

15. Top+Bottom on single stencil

16. Sencil Polishing: Electropolishing 17. Fiducials: Etched Through

18. Engrave Text

19. Impedance controlled differential pair

traces are 10.22 mil. 20. Differential pair impedance shall be 100 ohm +/-10%

## **BOARD CHARACTERISTICS**

Copper Layer Count: Board Thickness: 1.5981 mm

Board overall dimensions: 109.8550 mm x 78.9940 mm

Min hole diameter: 0.3000 mm Min track/spacing: 0.2540 mm / 0.1963 mm

Copper Finish: ENIG Impedance Control: Yes Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Green	3.3	0
F.Cu	copper		0.035052 mm		1	0
Dielectric	prepreg	3313	0.106934 mm	FR4 natural	4.5	0.02
Dielectric	prepreg	3313	0.099314 mm		1	0
In1.Cu	copper		0.01524 mm		1	0
Dielectric	core	1.1mm H/HOZ	1.065 mm	Not specified	4.5	0.02
In2.Cu	copper		0.01524 mm		1	0
Dielectric	prepreg	3313	0.099314 mm	Not specified	4.5	0.02
Dielectric	prepreg	3313	0.106934 mm		1	0
B.Cu	copper		0.035052 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0



## 971 Spartan Robotics

File: NX-J401-Adapter.kicad\_pcb

Title: NX Adapter Board

Size: B Date: 2024-08-10 KiCad E.D.A. 8.0.4 Rev: 3 Page: 1/1